

OptoTEC™ OT Series Thermoelectric Cooler

Note: This product is not recommended for new designs.

This product series has been replaced with the OptoTEC $^{\text{\tiny{TM}}}$ OTX Series. The recommended replacement is:

MFG Part Number: 387006794

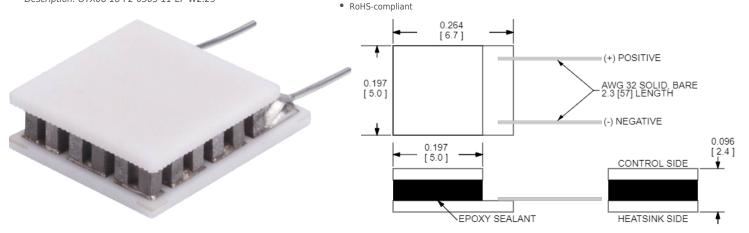
Description: OTX08-18-F2-0505-11-EP-W2.25

Features

- Miniature geometric sizes
- Precise temperature control
- Reliable solid-state operationNo sound or vibration
- DC operation

res Applications

- Thermoelectric Cooling for CMOS Sensors
- Cooling Solutions for Autonomous Systems
- Heads-Up Displays, Imaging Sensors



CERAMIC MATERIAL: Al₂O₃

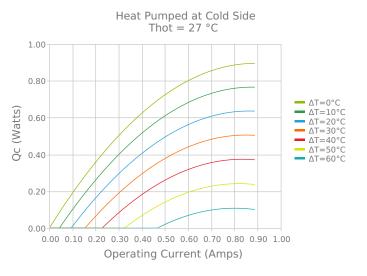
SOLDER CONSTRUCTION: 138°C, BiSn

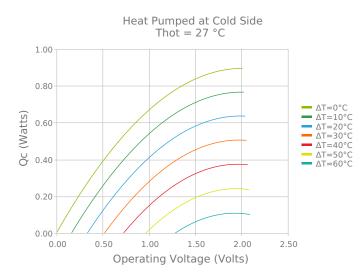
INCHES [MM]

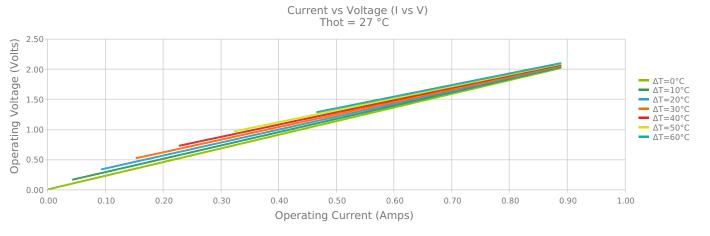
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

ELECTRICAL AND THERMAL PERFORMANCE

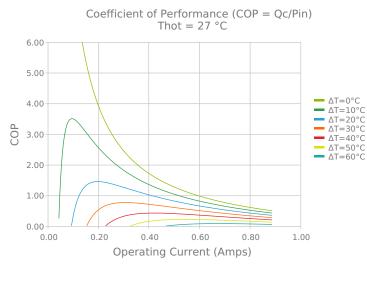
For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

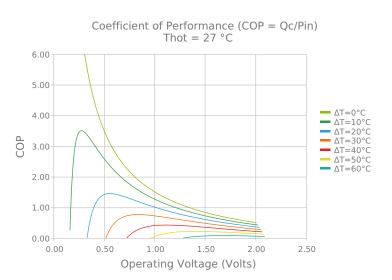


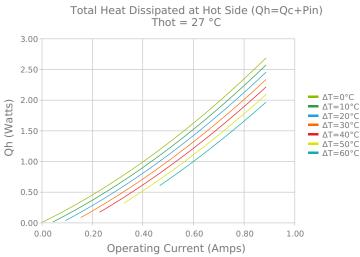


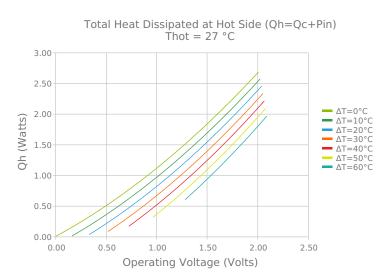


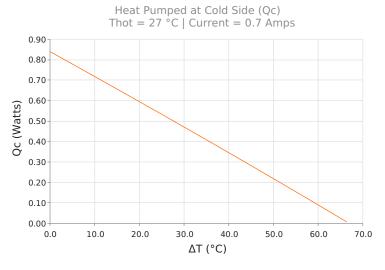


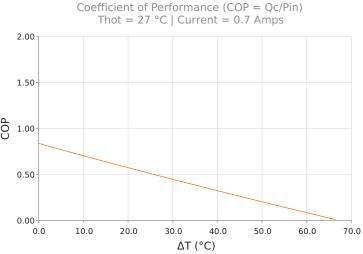














SPECIFICATIONS*

Hot Side Temperature

 $Qcmax (\Delta T = 0)$

 $\Delta T max (Qc = 0)$

Imax (I @ ATmax)

Vmax (V @ Δ Tmax)

Module Resistance

Max Operating Temperature

Weight

27.0 °C	35.0 °C	50.0 °C
0.9 Watts	0.9 Watts	1.0 Watts
68.0°C	70.9°C	76.0°C
0.8 Amps	0.8 Amps	0.8 Amps
1.9 Volts	2.0 Volts	2.1 Volts
2.27 Ohms	2.36 Ohms	2.54 Ohms
80 °C		
1.0 gram(s)		

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
11	2.438 ±0.127 mm 0.096 ± 0.0050 in	0.051 mm / 0.051 mm 0.002 in / 0.002 in	Lapped	Lapped	50.8 mm 2.00 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

- 1. Max operating temperature: 80°C
- 2. Do not exceed Imax or Vmax when operating module
- 3. Reference assembly guidelines for recommended installation
- 4. Solder tinning also available on metallized ceramics

Any information furnished by Laird and its agents, whether in specifications, data sheets, product catalogues or otherwise, is believed to be (but is not warranted as being) accurate and reliable, is provided for information only and does not form part of any contract with Laird. All specifications are subject to change without notice. Laird assumes no responsibility and disclaims all liability for losses or damages resulting from use of or reliance on this information. All Laird products are sold subject to the Laird Terms and Conditions of sale (including Laird's limited warranty) in effect from time to time, a copy of which will be furnished upon request.

© Copyright 2019-2022 Laird Thermal Systems, Inc. All rights reserved. Laird[™], the Laird Ring Logo, and Laird Thermal Systems[™] are trademarks or registered trademarks of Laird Limited or its subsidiaries.

OptoTEC™ is a trademark of Laird Thermal Systems, Inc. All other marks are owned by their respective owners.

Revision: 00 Date: 06-01-2022

Print Date: 06-15-2022

^{*} Specifications reflect thermoelectric coefficients updated March 2020